

| L Number | Hits   | Search Text  | DB              | Time stamp       |
|----------|--------|--|-----------------|------------------|
| -        | 114936 | "three dimensional" or "3 dimensional" or "3-D" or "3 D" or "three-dimensional" or "3-dimensional"   | USPAT; US-PGPUB | 2002/04/17 16:27 |
| -        | 923    | ("three dimensional" or "3 dimensional" or "3-D" or "3 D" or "three-dimensional" or "3-dimensional") and ((bond or bonding) SAME "thin film")  | USPAT; US-PGPUB | 2002/04/17 16:33 |
| -        | 274    | ((("three dimensional" or "3 dimensional" or "3-D" or "3 D" or "three-dimensional" or "3-dimensional") and ((bond or bonding) SAME "thin film")) and (UV or irradiating or irradiate))   | USPAT; US-PGPUB | 2002/04/17 16:33 |
| -        | 157    | ((("three dimensional" or "3 dimensional" or "3-D" or "3 D" or "three-dimensional" or "3-dimensional") and ((bond or bonding) SAME "thin film")) and (UV or irradiating or irradiate)) and semiconductor transfer with substrate with device   | USPAT; US-PGPUB | 2002/04/17 16:31 |
| -        | 3417   | transfer with substrate with device  | USPAT; US-PGPUB | 2002/04/17 16:32 |
| -        | 4068   | (transfer or transferring) with substrate with device  | USPAT; US-PGPUB | 2002/04/17 16:32 |
| -        | 331    | ((transfer or transferring) with substrate with device) and ("three dimensional" or "3 dimensional" or "3-D" or "3 D" or "three-dimensional" or "3-dimensional")   | USPAT; US-PGPUB | 2002/04/17 16:32 |
| -        | 121    | ((transfer or transferring) with substrate with device) and ("three dimensional" or "3 dimensional" or "3-D" or "3 D" or "three-dimensional" or "3-dimensional") and "thin film"   | USPAT; US-PGPUB | 2002/04/17 17:00 |
| -        | 55     | ((((transfer or transferring) with substrate with device) and ("three dimensional" or "3 dimensional" or "3-D" or "3 D" or "three-dimensional" or "3-dimensional")) and "thin film") and (UV or irradiating or irradiate)  | USPAT; US-PGPUB | 2002/04/17 16:33 |
| -        | 66     | ((((transfer or transferring) with substrate with device) and ("three dimensional" or "3 dimensional" or "3-D" or "3 D" or "three-dimensional" or "3-dimensional")) and "thin film") NOT (((((transfer or transferring) with substrate with device) and ("three dimensional" or "3 dimensional" or "3-D" or "3 D" or "three-dimensional" or "3-dimensional")) and "thin film") and (UV or irradiating or irradiate)) | USPAT; US-PGPUB | 2002/04/17 17:08 |
| -        | 28     | "thin film device" SAME transfer SAME substrate  | USPAT; US-PGPUB | 2002/04/17 18:02 |
| -        | 1605   | "thin film" SAME transfer SAME substrate   | USPAT; US-PGPUB | 2002/04/17 18:03 |
| -        | 835    | ("thin film" SAME transfer SAME substrate) and (bonding or bonded or bond)   | USPAT; US-PGPUB | 2002/04/17 18:03 |
| -        | 502    | ((("thin film" SAME transfer SAME substrate) and (bonding or bonded or bond)) and semiconductor  | USPAT; US-PGPUB | 2002/04/17 18:06 |
| -        | 3      | ("5821138"   "6127199"   "6143582").PN.  | USPAT           | 2002/04/17 18:14 |